

FIG. 1
(PRIOR ART)

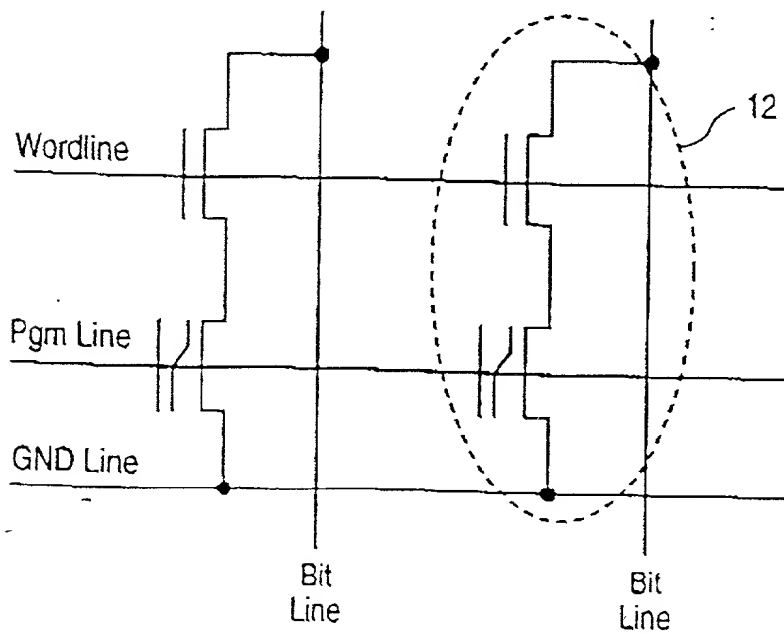


FIG. 2
(PRIOR ART)

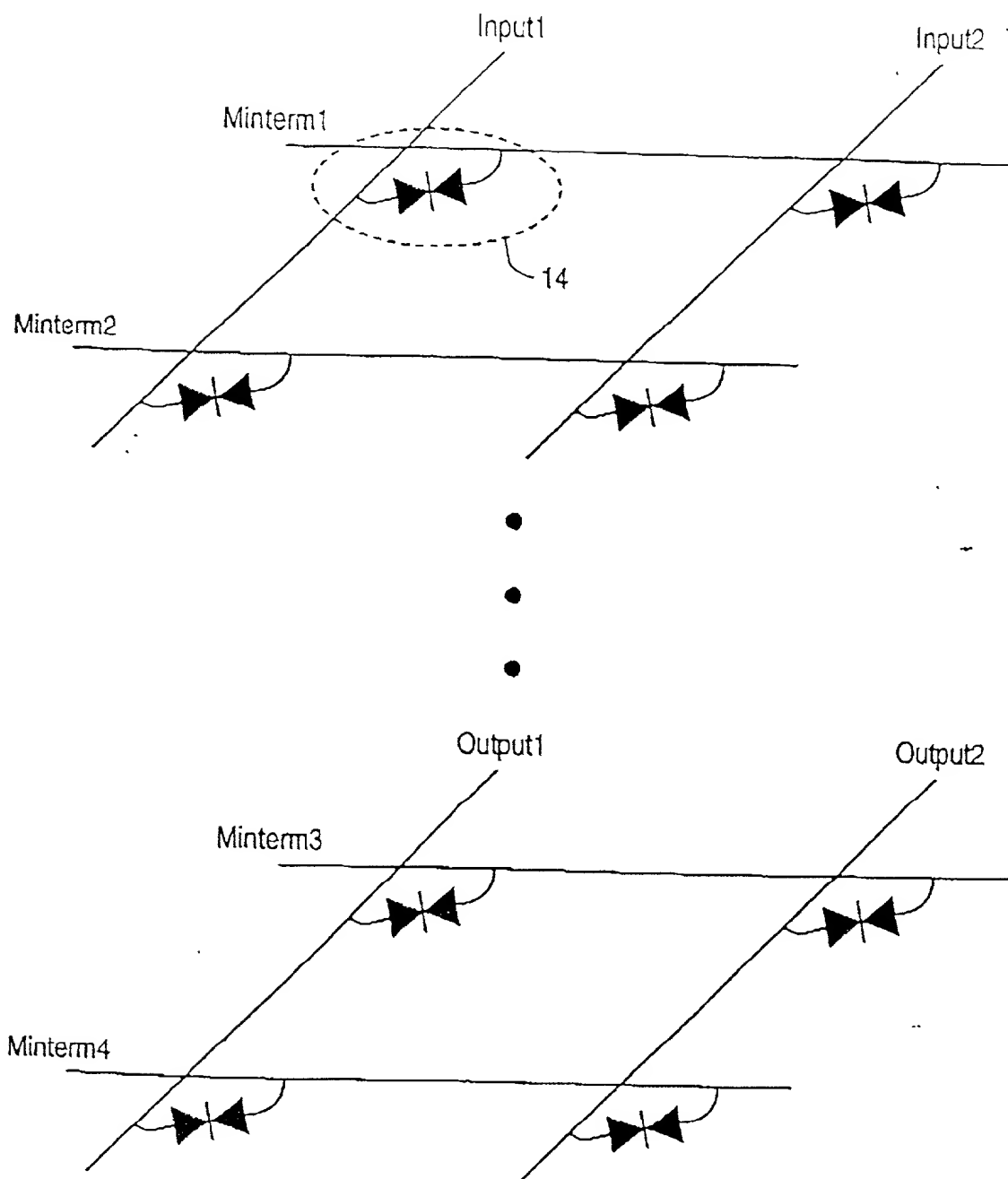


FIG. 3
(PRIOR ART)

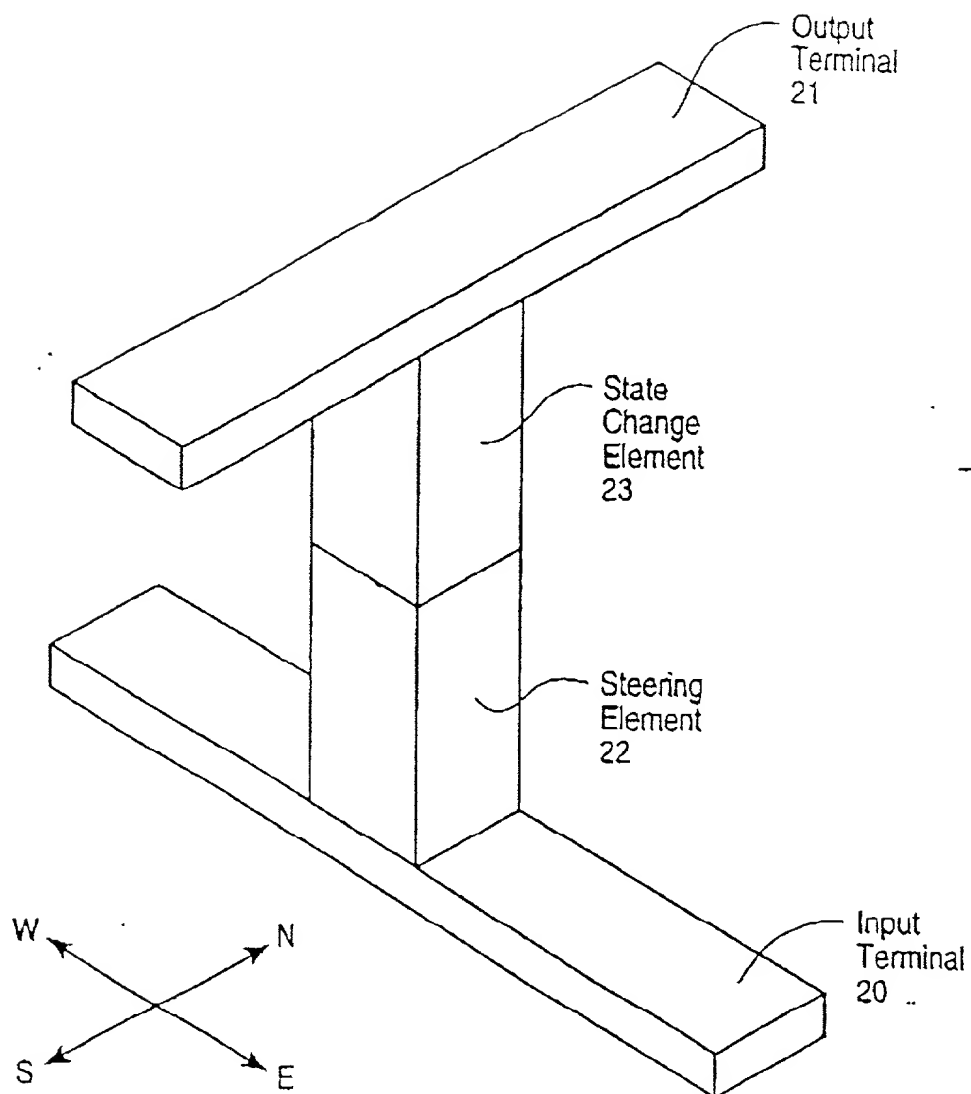


FIG. 4(a)

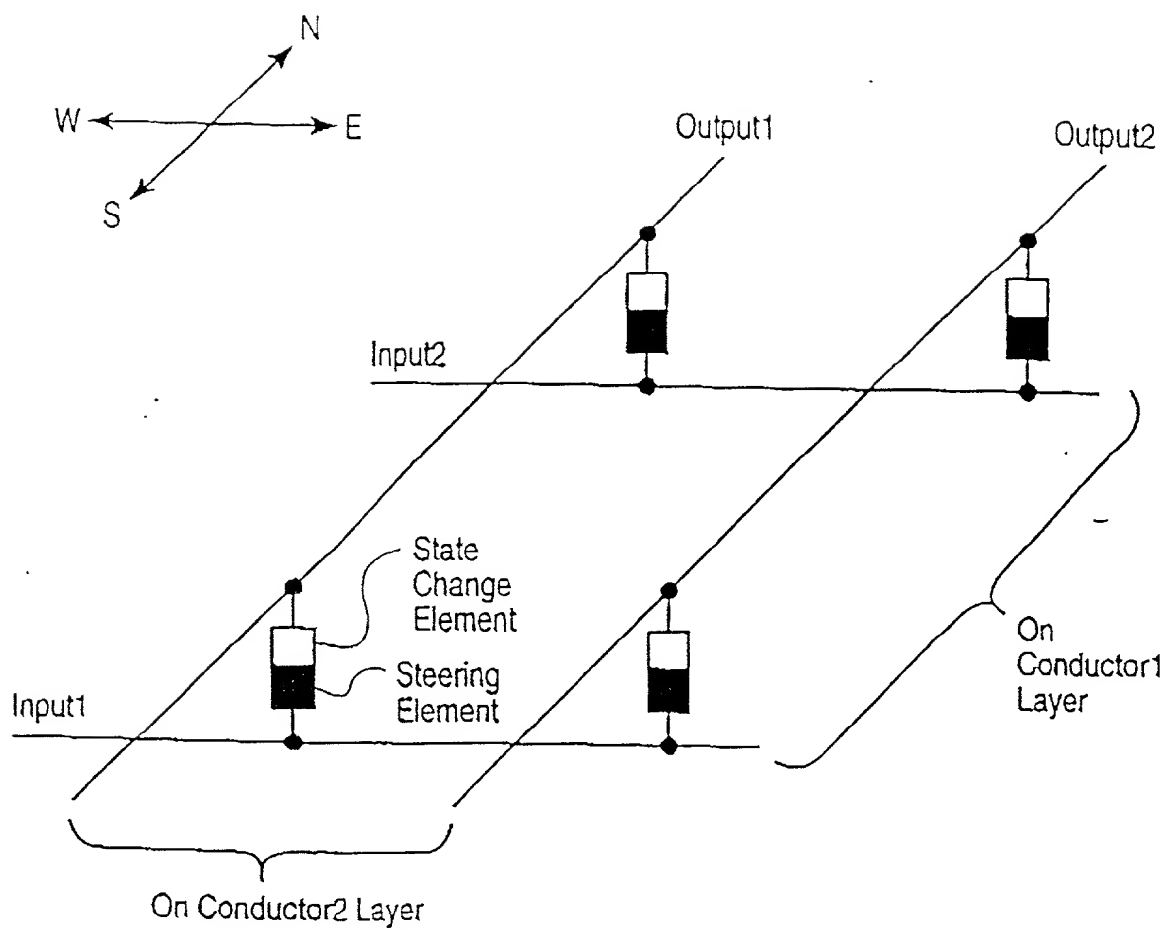


FIG. 4(b)

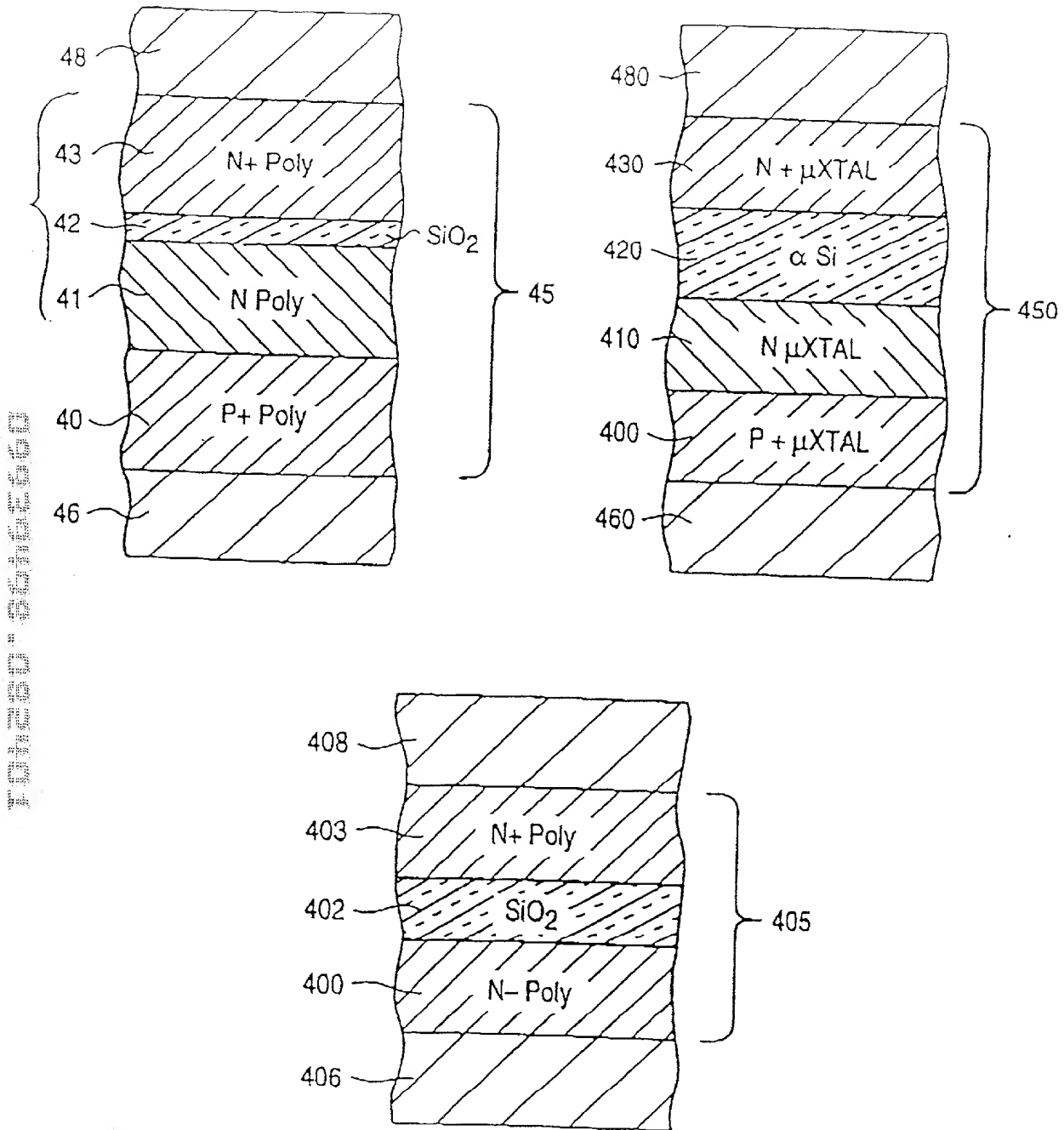


FIG. 6(a)

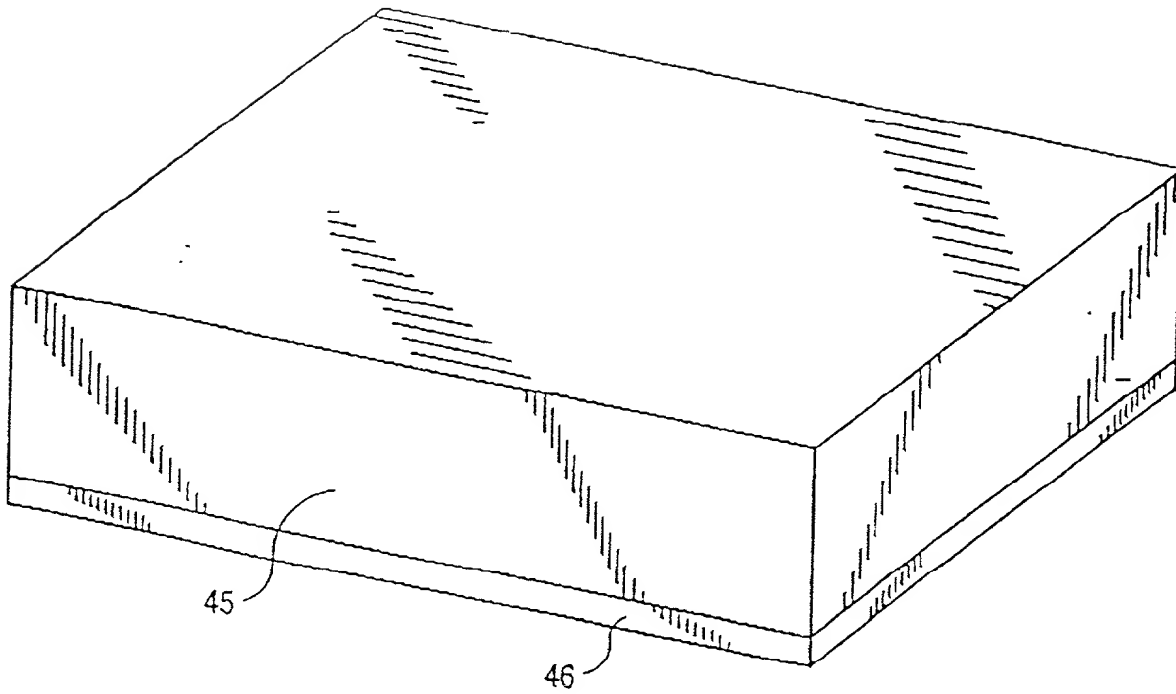


FIG. 6(b)

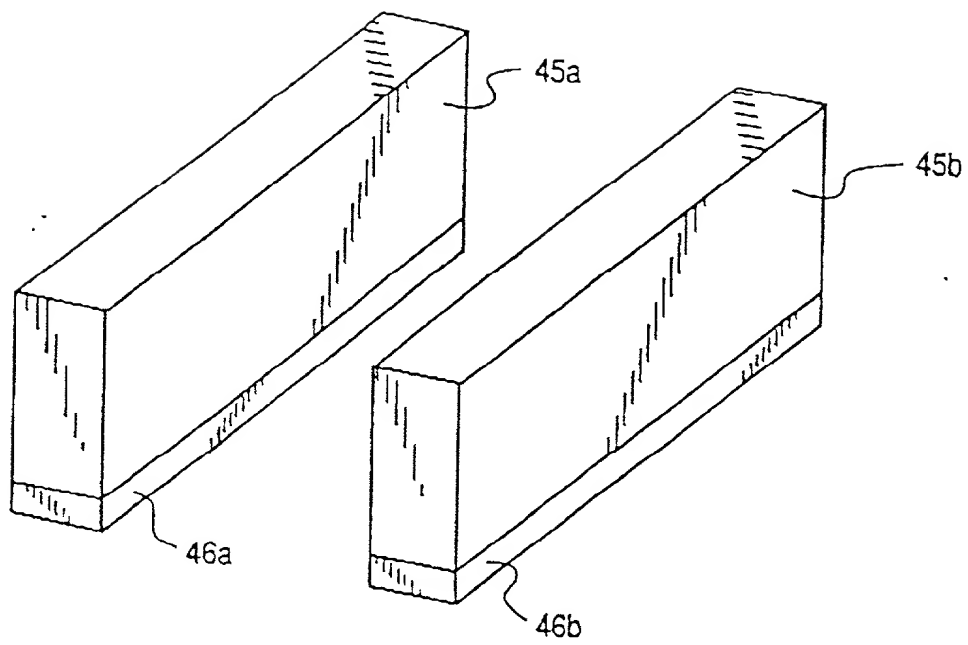


FIG. 6(c)

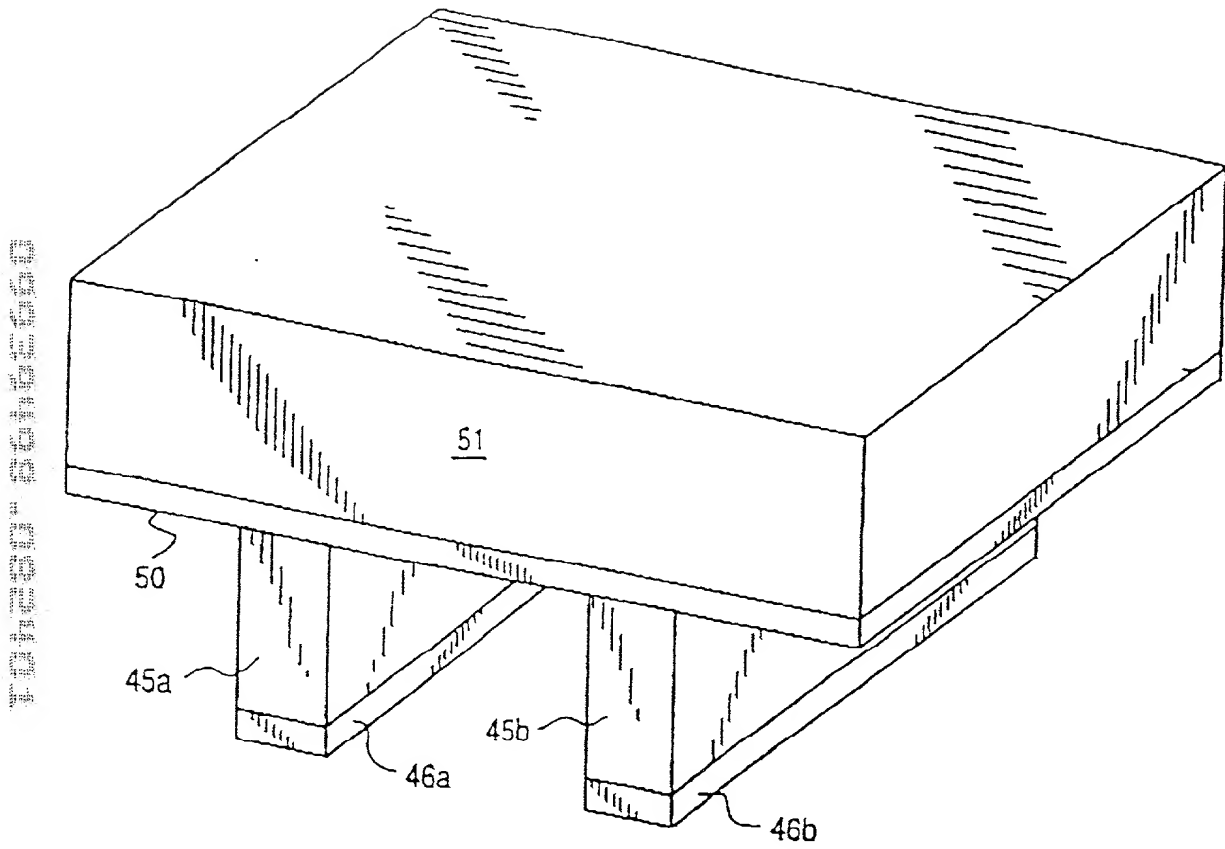


FIG. 6(d)

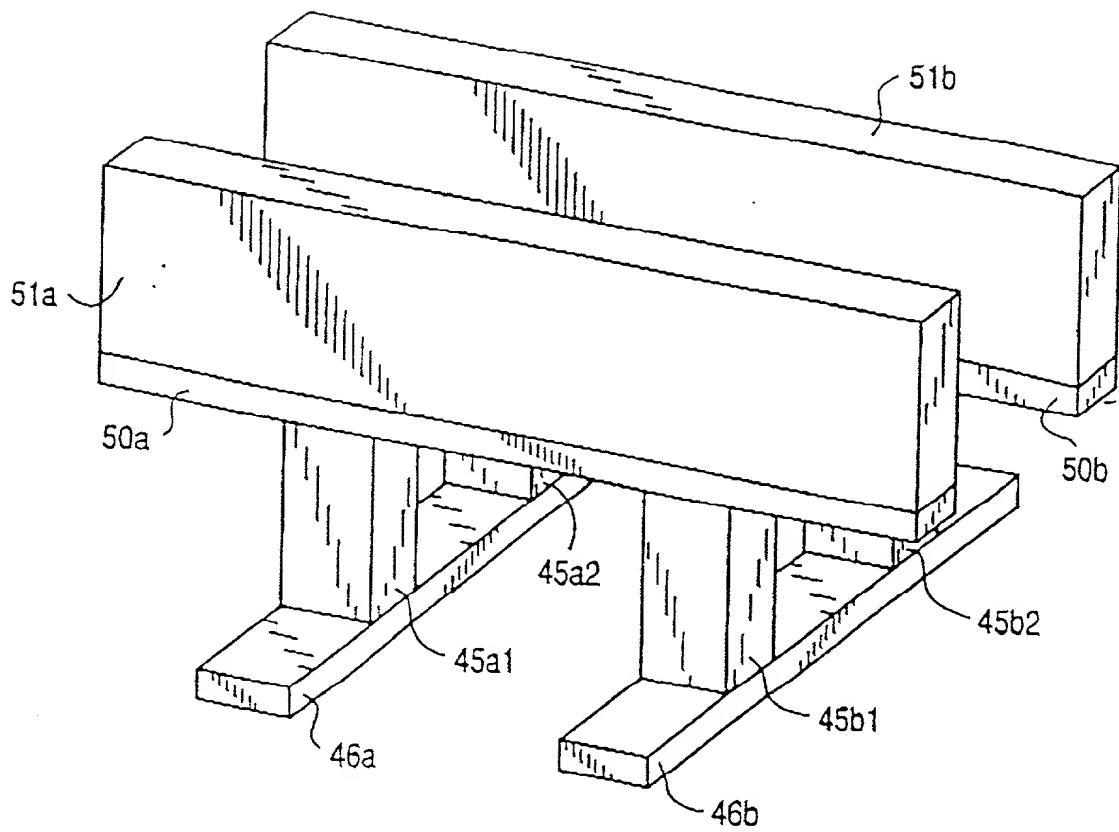


FIG. 6(e)

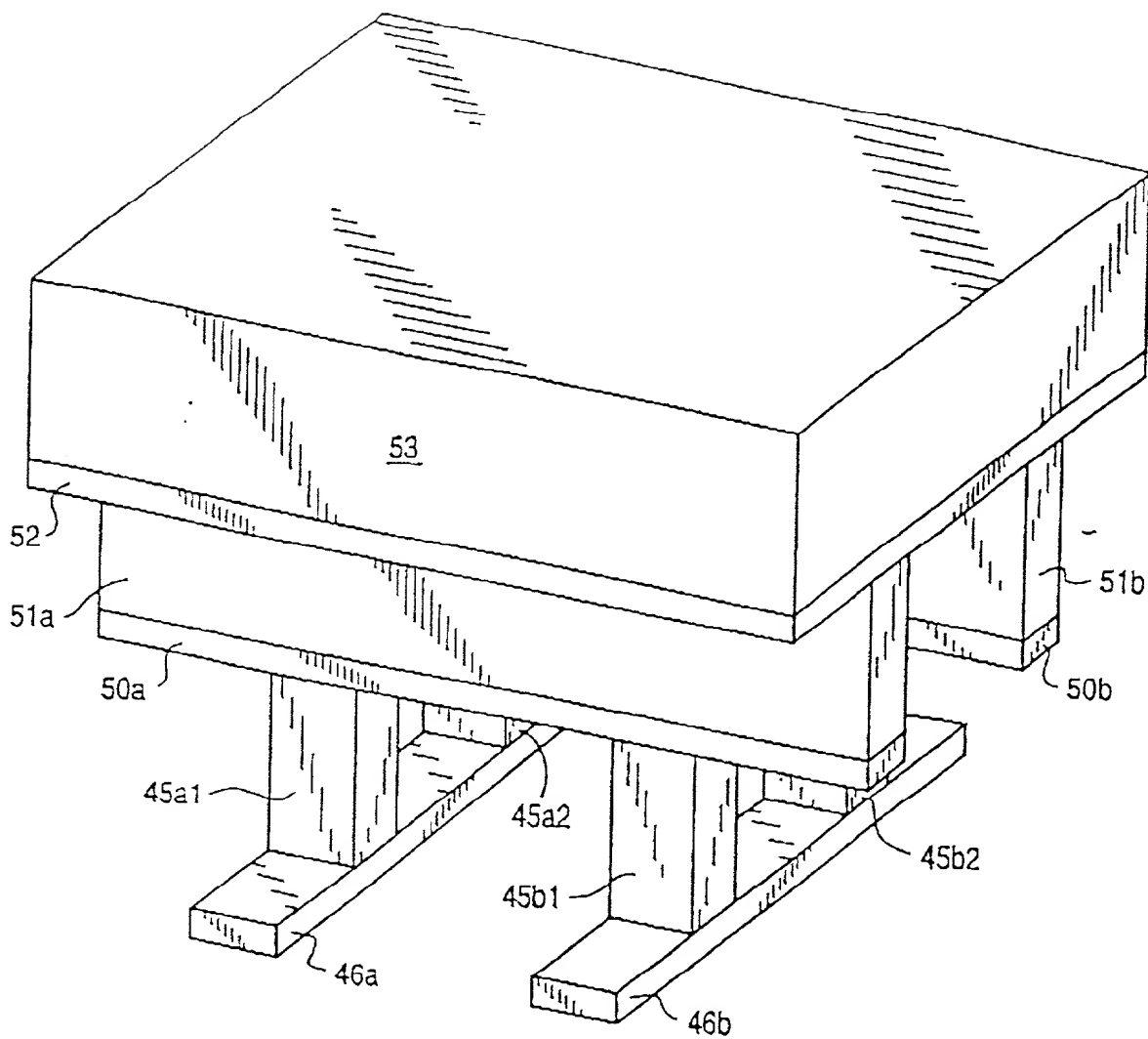


FIG. 6(f)

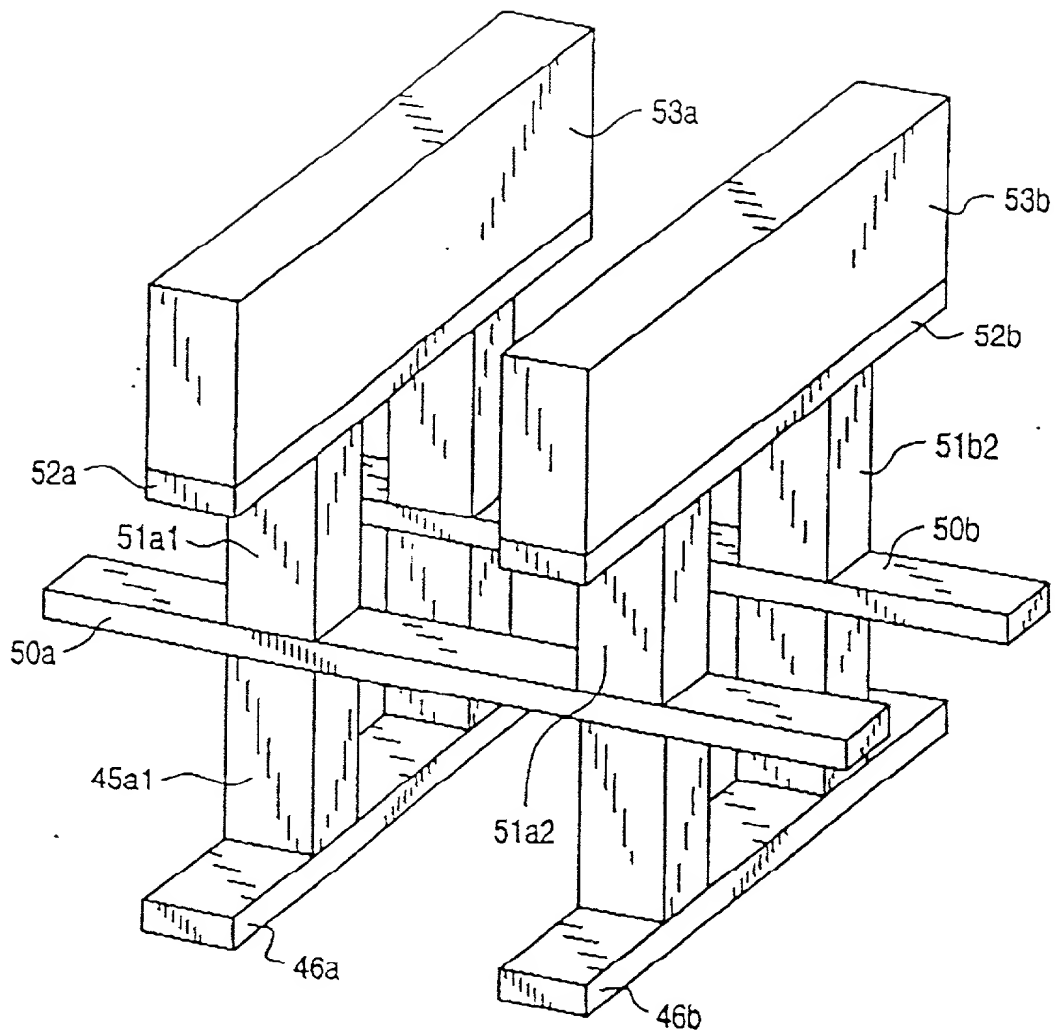


FIG. 6(g)

The diagram illustrates a cross-section of a multi-layer printed circuit board (PCB) with seven conductive layers, labeled Conductor1 through Conductor7 from bottom to top. The layers are separated by non-conductive prepreg. Vertical pillars connect the layers. Pillar1 is located between Conductor1 and Conductor2. Pillar2 is between Conductor2 and Conductor3. Pillar3 is between Conductor3 and Conductor4. Pillar4 is between Conductor4 and Conductor5. Pillar5 is between Conductor5 and Conductor6. Pillar6 is between Conductor6 and Conductor7. Arrows point from the labels to the corresponding pillars. The pillars are shown as vertical structures with horizontal segments at each layer interface, indicating they are through-hole or microvia structures.

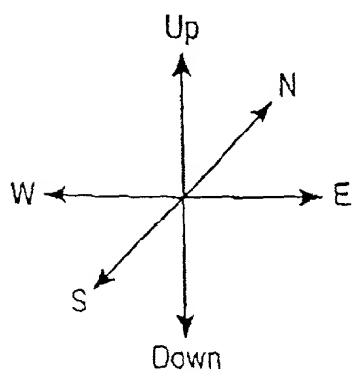


FIG. 7

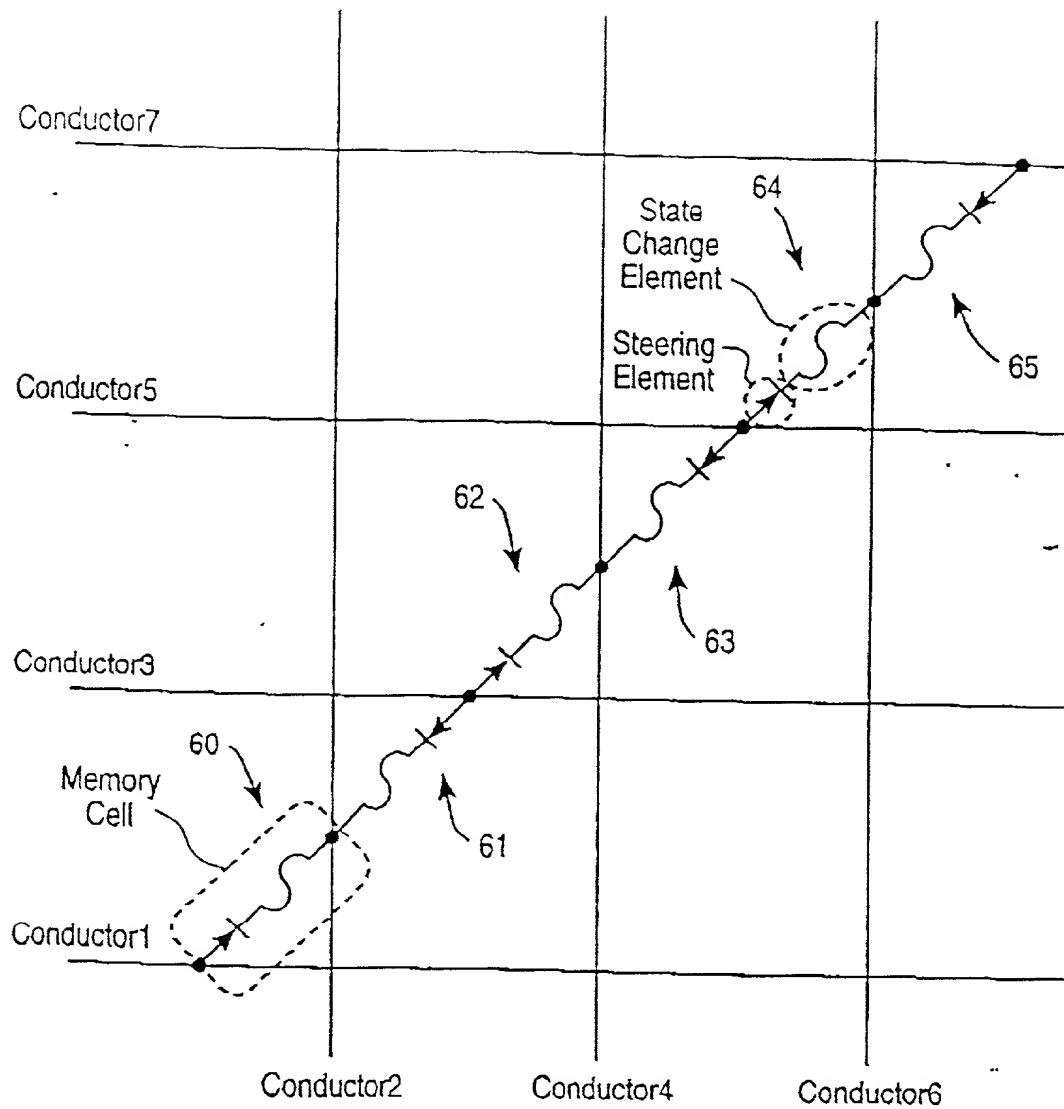


FIG. 8(b)

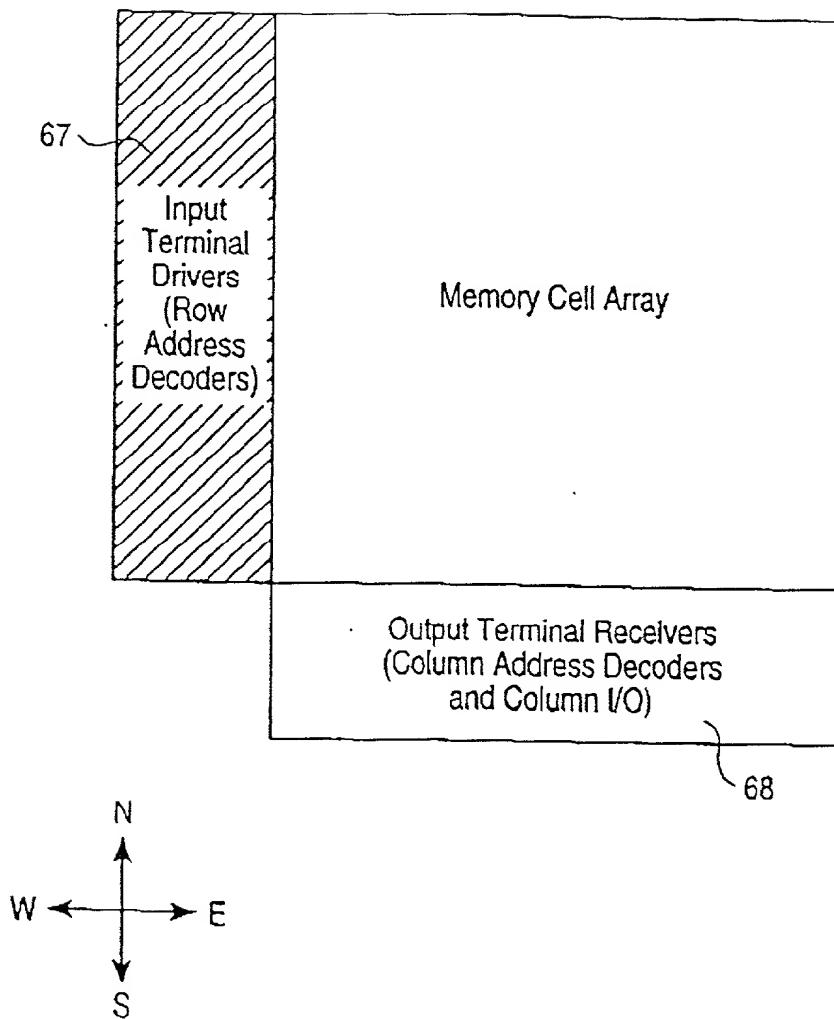


FIG. 9(a)

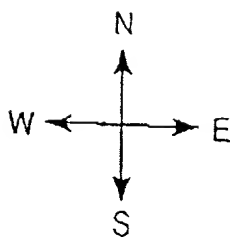
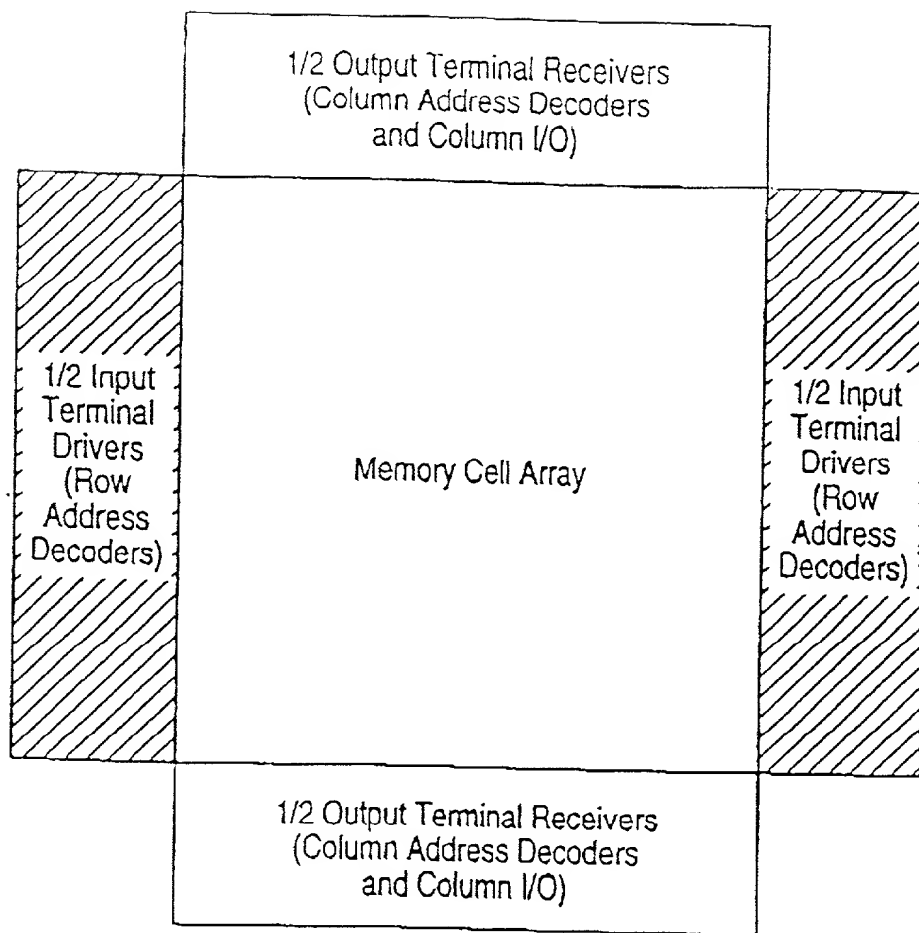


FIG. 9(b)

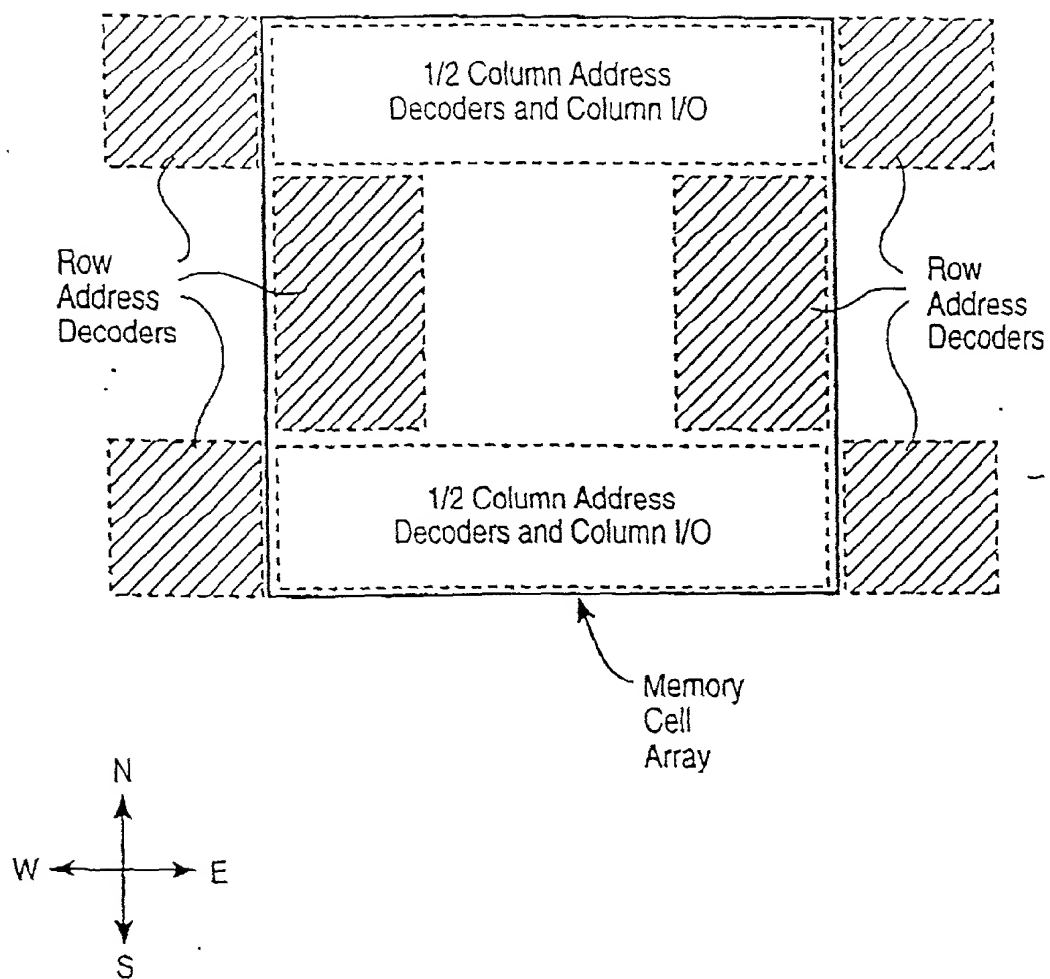
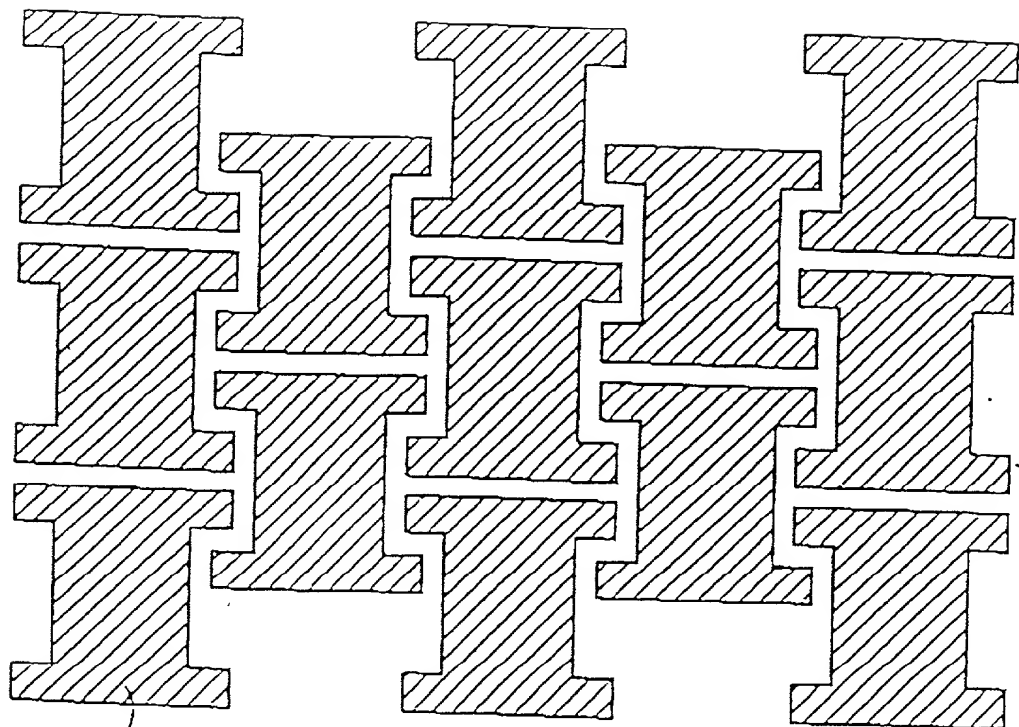


FIG. 9(c)



One Subarray

FIG. 9(d)

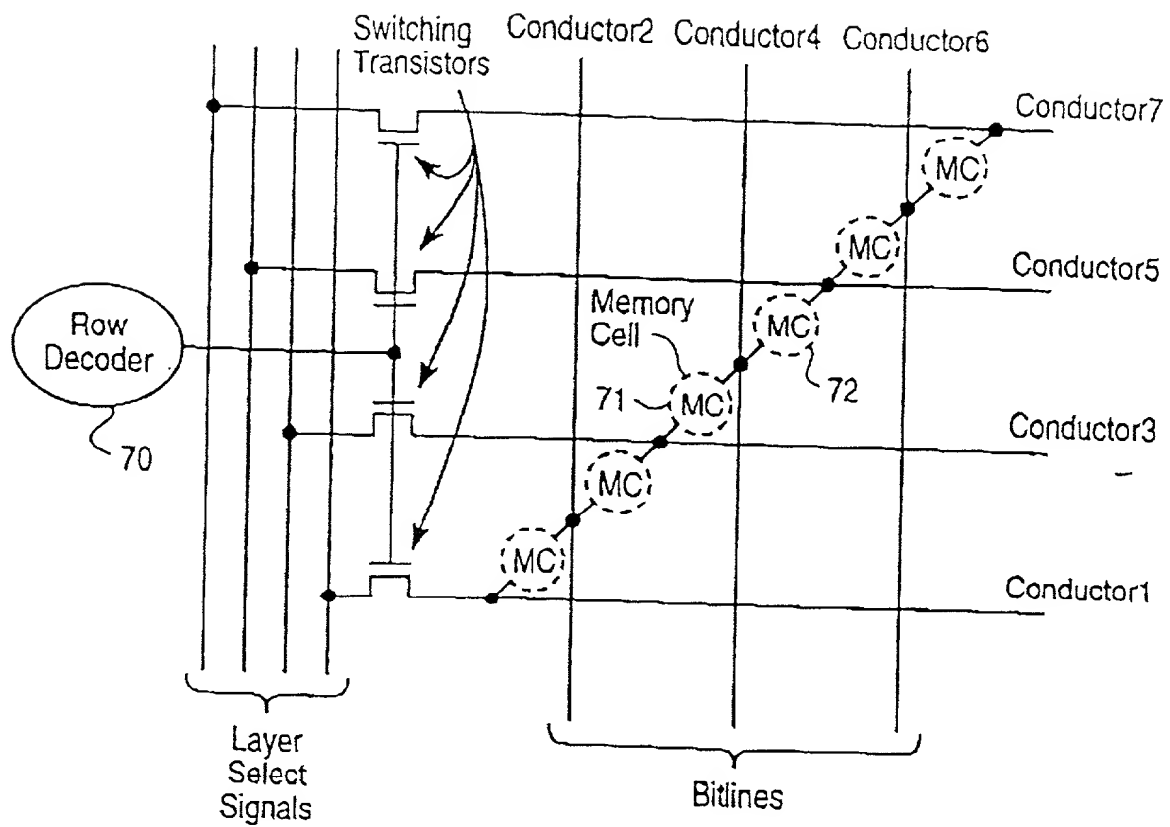


FIG. 10(a)

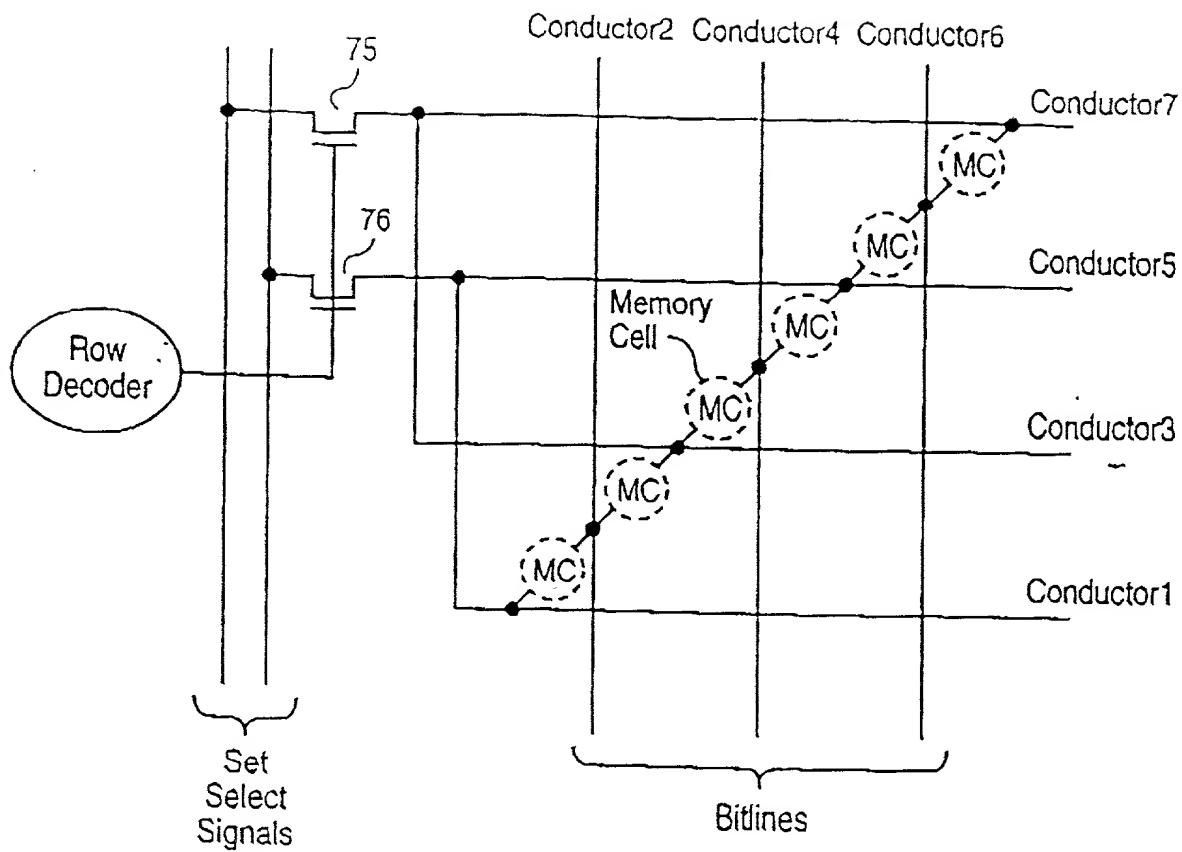


FIG. 10(b)

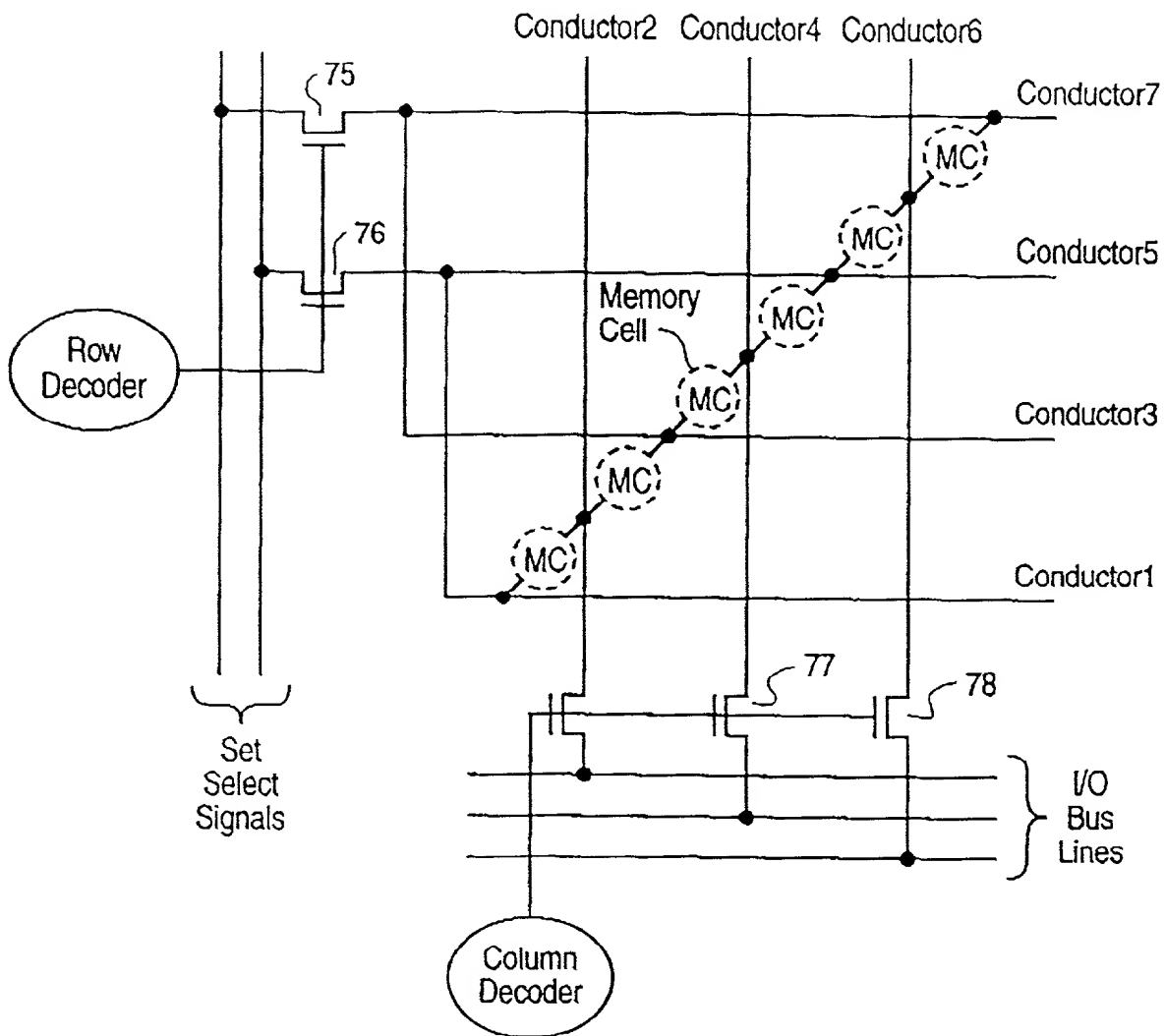


FIG. 11

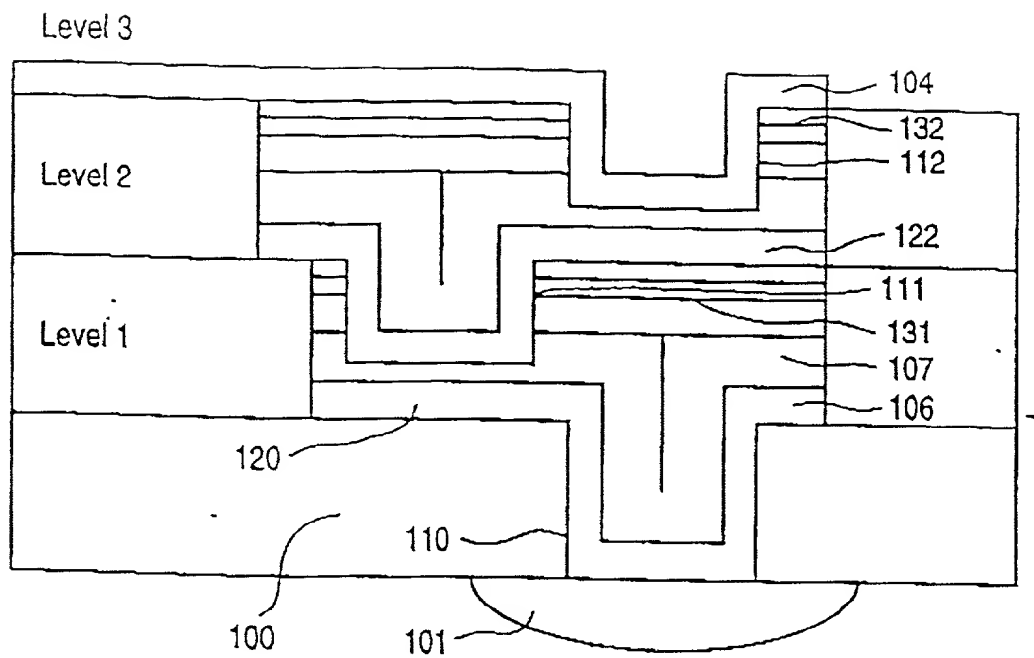


FIG. 12

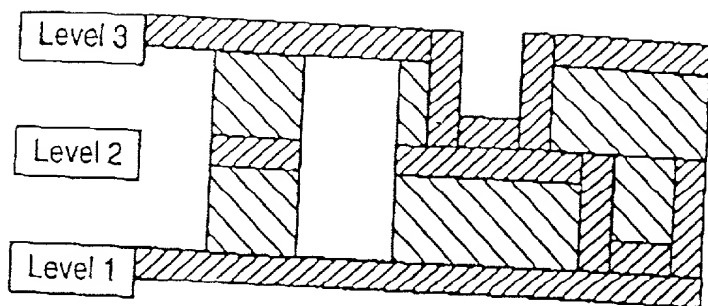


FIG. 13(a)

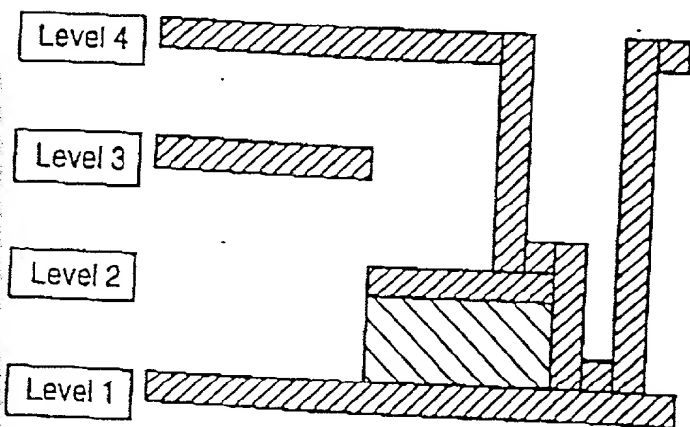


FIG. 13(b)

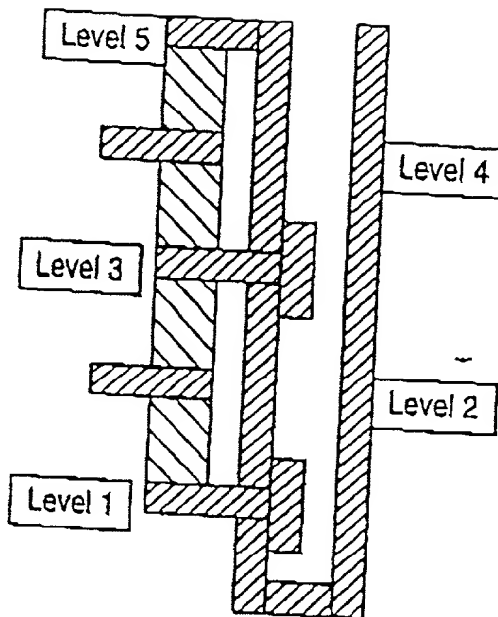


FIG. 13(c)

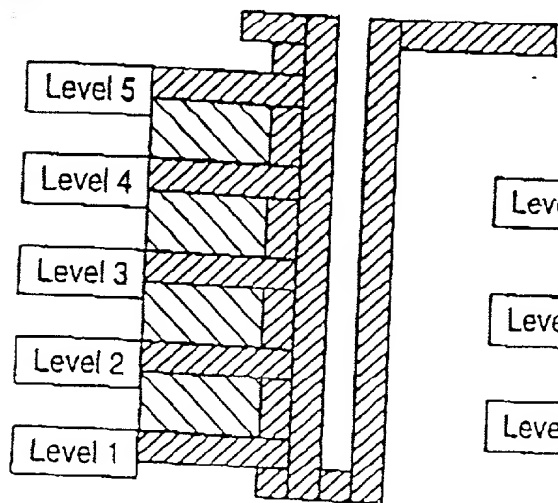


FIG. 13(d)

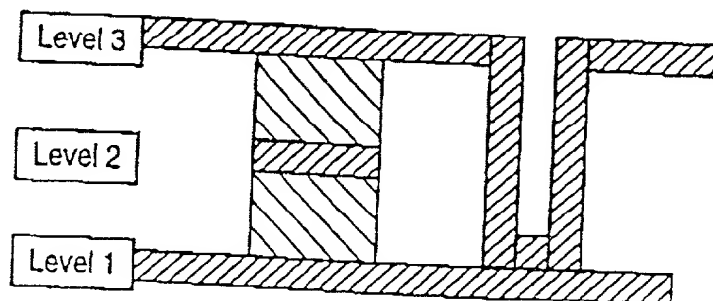


FIG. 13(e)